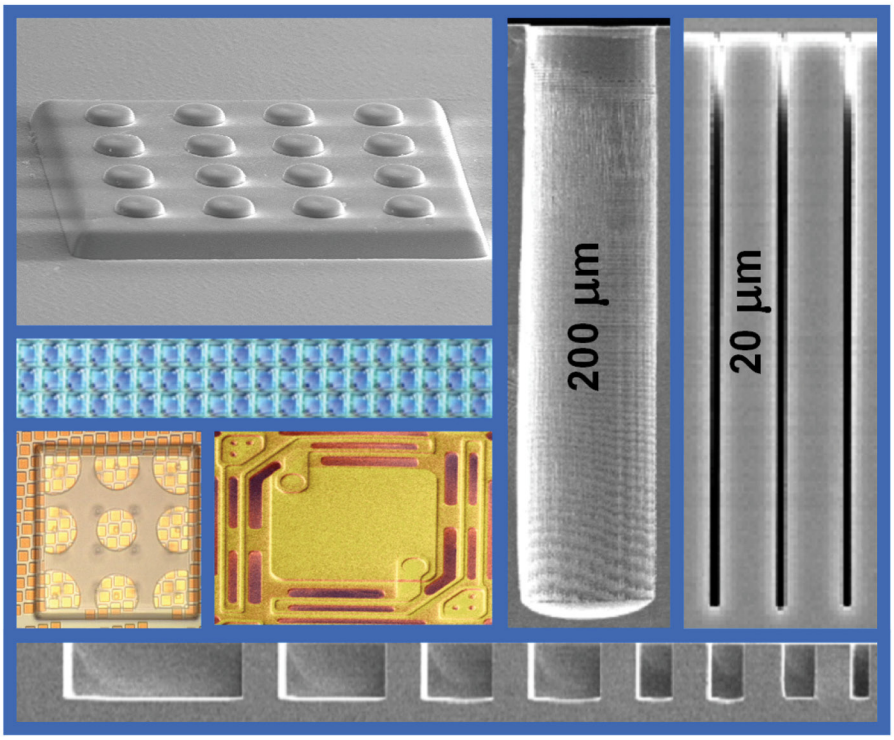
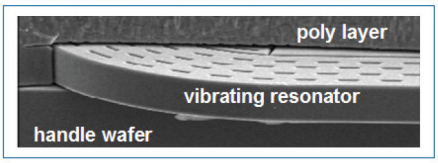
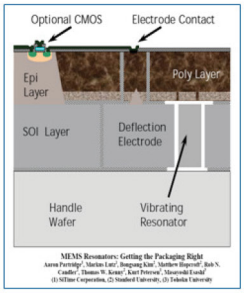
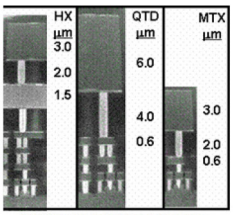
TOWERJAZZ
The Global Specialty Foundry Leader

MEMS Foundry
Partnering for Success

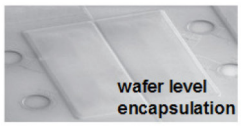


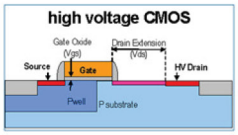






interconnect schemes





TowerJazz provides world-class “Foundry MEMS Enablement” solutions combined with high volume 150mm and 200mm CMOS wafer manufacturing. We integrate custom MEMS with our specialty processes to address complex wireless and consumer electronics markets. We focus on a collaborative partnership model and apply our foundry experience, silicon MEMS processes and customer oriented team to enable the successful and rapid implementation of both 150mm and 200mm MEMS manufacturing, including both prototype and ramp to volume production. We continue to augment our portfolio of specialty silicon technology adding MEMS manufacturing to our existing suite of analog and RF CMOS, high speed SiGe, and high voltage technology enhancing the ability of our customers to create and bring to market more highly integrated analog products.

Wafer Process Capabilities

Etch

Deep Si, deep oxide, thick metal etches

- deep trench isolation
- Si MEMS <1µm, 10–20µm deep
- deeper etches (>100µm)
- thick metal, deep via

Release

Multiple Tools and methods:

- dielectrics, group IV (Si), polymers
- gas or vapor methods

Encapsulation

Some call this wafer level packaging or thin film seal.

- Methods for Si MEMS and RF MEMS

Integration

- Same wafer CMOS + MEMS

Manufacturing

- ISO Standards
- Development execution in a CMOS manufacturing line

For more information, please contact: Info_Mems@towerjazz.com